

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XC6371CxxxDR-G  
Typical Mass: 6 mg

| Part name    | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|---------------|------------|------------|
| Silicon chip | 1.049      | Silicon       | 174800     | 7440-21-3  |
|              |            |               |            |            |
| Lead pad     | 1.100      | Nickel        | 183400     | 7440-02-0  |
|              | 0.087      | Silver        | 14600      | 7440-22-4  |
|              | 0.016      | Gold          | 2700       | 7440-57-5  |
|              |            |               |            |            |
| Die attach   | 0.016      | Epoxy Resin   | 2700       | —          |
|              | 0.012      | Silica        | 2100       | 60676-86-0 |
|              |            |               |            |            |
| Bonding wire | 0.040      | Gold          | 6700       | 7440-57-5  |
|              |            |               |            |            |
| Resin        | 3.311      | Silica        | 551800     | 60676-86-0 |
|              | 0.202      | Epoxy Resin   | 33700      | —          |
|              | 0.166      | Phenol Resin  | 27600      | —          |
|              |            |               |            |            |

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."